

Integrated Circuit with Re-Route Layer and Stacked Die Assembly

ABSTRACT OF THE DISCLOSURE

An apparatus and a method of manufacture for a stacked-die assembly. A first die is placed on a substrate such that the backside of the die, *i.e.*, the side opposite the side with the bond pads, is coupled to the substrate, preferably by an adhesive. Wire leads electrically couple the bond pads of the first die to contacts on the substrate. A second die is placed on the first die, and wire leads electrically couple the bond pads of the second die to contacts on the substrate. Preferably, a spacer is placed between the first die and the second die. Additional dies may be stacked on the second die.